

Silicon Schottky Diode

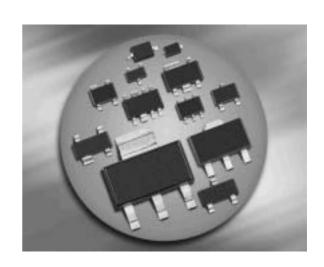
- High current rectifier Schottky diode with very low V_F drop (typ. 0.24 V at $I_F = 10$ mA)
- For power supply applications
- For clamping and protection in low voltage applications
- For detection and step-up-conversion
- Pb-free (RoHS compliant) package 1)
- Qualified according AEC Q101





BAT60B





ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Туре	Package	Configuration	Marking
BAT60B	SOD323	single	white/5

Maximum Ratings at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Value	Unit	
Diode reverse voltage ²⁾	V_{R}	10	V	
Forward current	I _F	3	А	
Non-repetitive peak surge forward current	I _{FSM}	5		
(<i>t</i> ≤ 10ms)				
Total power dissipation	P _{tot}	1350	mW	
<i>T</i> _S ≤ 28°C				
Junction temperature	T _i	150	°C	
Operating temperature range	T _{op}	-55 125		
Storage temperature	T _{stq}	-55 150		

¹Pb-containing package may be available upon special request

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 $^{^2}$ For $T_A > 25$ $^{\circ}$ C the derating of V_R has to be considered. Please refer to curve Permissible reverse voltage.



Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R _{thJS}	≤ 90	K/W

Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics	_				
Reverse current ²⁾	I _R				μA
$V_{R} = 5 \; V$		-	5	15	
$V_{R} = 8 \; V$		-	10	25	
$V_{R} = 5 \text{ V}, \ T_{A} = 80 \text{ °C}$		-	100	800	
$V_{R} = 8 \text{ V}, \ T_{A} = 80 \text{ °C}$		-	410	1500	
Forward voltage ²⁾	V _F				V
$I_{\rm F}$ = 10 mA		0.2	0.24	0.3	
$I_{\rm F} = 100 \text{mA}$		0.26	0.32	0.38	
$I_{\rm F} = 500 \text{mA}$		0.32	0.4	0.5	
$I_{\rm F} = 1000 \text{mA}$		0.36	0.48	0.6	
AC Characteristics		-			
Diode capacitance	C _T	12	25	30	pF
$V_{R} = 5 \text{ V}, f = 1 \text{ MHz}$					

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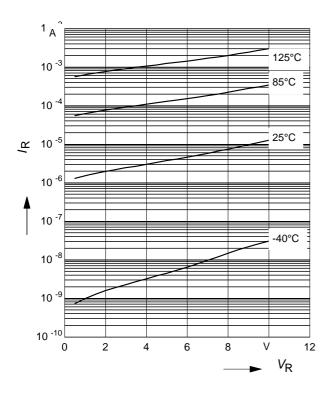
 $^{^{1}}$ For calculation of R_{thJA} please refer to Application Note Thermal Resistance

²Pulsed test: t_p = 300 µs; D = 0.01



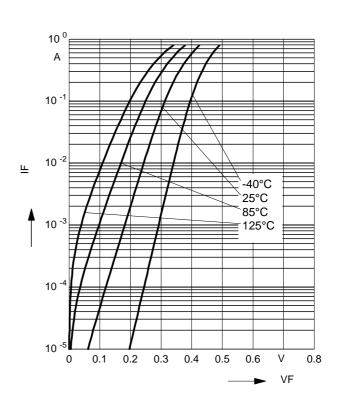
Reverse current $I_R = f(V_R)$

 T_A = Parameter



Forward current $I_F = f(V_F)$

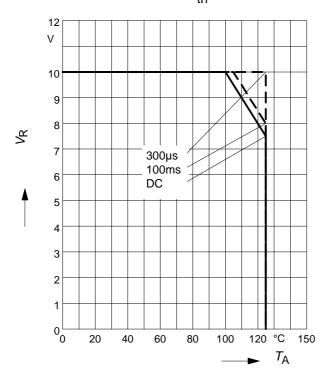
 T_A = Parameter



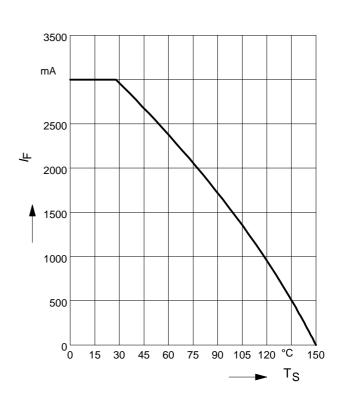
Permissible Reverse voltage $V_R = f(T_A)$

 t_p = Parameter; duty cycle < 0.01

Device mounted on PCB with R_{th} = 160 K/W



Forward current $I_F = f(T_S)$





Permissible Puls Load $R_{thJS} = f(t_p)$

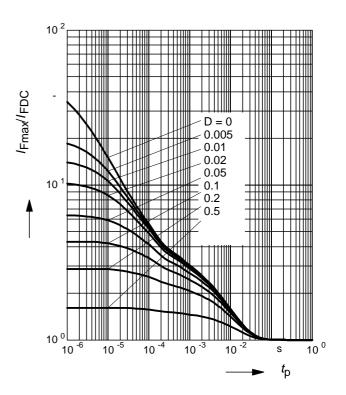
10 ² K/W 10 ¹ 0.5 0.2 0.1 0.05 0.2 0.1 0.05 0.02 0.1 0.005 D = 0

Permissible Pulse Load

$$I_{\text{Fmax}}/I_{\text{FDC}} = f(t_{\text{p}})$$

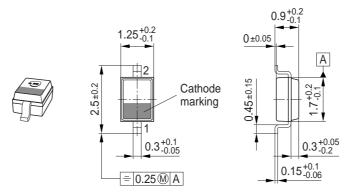
10 ⁰

10

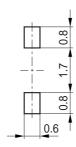




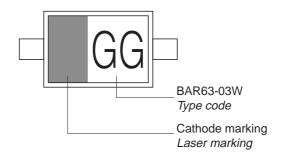
Package Outline



Foot Print

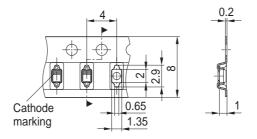


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel





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